

ON Semiconductor

Is Now

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BUL147

SWITCHMODE™

NPN Bipolar Power Transistor For Switching Power Supply Applications

The BUL147 have an applications specific state-of-the-art die designed for use in electric fluorescent lamp ballasts to 180 Watts and in Switchmode Power supplies for all types of electronic equipment.

Features

- Improved Efficiency Due to Low Base Drive Requirements:
 - ◆ High and Flat DC Current Gain
 - ◆ Fast Switching
 - ◆ No Coil Required in Base Circuit for Turn-Off (No Current Tail)
- Parametric Distributions are Tight and Consistent Lot-to-Lot
- Two Package Choices: Standard TO-220 or Isolated TO-220
- Pb-Free Package is Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Sustaining Voltage	V_{CEO}	400	Vdc
Collector-Base Breakdown Voltage	V_{CES}	700	Vdc
Emitter-Base Voltage	V_{EBO}	9.0	Vdc
Collector Current – Continuous – Peak (Note 1)	I_C I_{CM}	8.0 16	Adc
Base Current – Continuous – Peak (Note 1)	I_B I_{BM}	4.0 8.0	Adc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	125 1.0	W W/ $^\circ\text{C}$
Operating and Storage Temperature	T_J, T_{stg}	-65 to 150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.0	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 5 Seconds	T_L	260	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

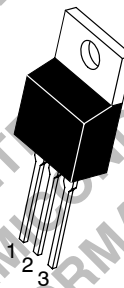
1. Pulse Test: Pulse Width = 5 ms, Duty Cycle $\leq 10\%$.



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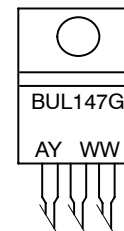
<http://onsemi.com>

POWER TRANSISTOR
8.0 AMPERES, 700 VOLTS,
45 AND 125 WATTS



TO-220AB
CASE 221A-09
STYLE 1

MARKING DIAGRAM



BUL147 = Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
BUL147	TO-220	50 Units / Rail
BUL147G	TO-220 (Pb-Free)	50 Units / Rail

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

BUL147

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit	
OFF CHARACTERISTICS						
Collector–Emitter Sustaining Voltage (I _C = 100 mA, L = 25 mH)	V _{CEO(sus)}	400	–	–	Vdc	
Collector Cutoff Current (V _{CE} = Rated V _{CEO} , I _B = 0)	I _{CEO}	–	–	100	μAdc	
Collector Cutoff Current (V _{CE} = Rated V _{CES} , V _{EB} = 0)	I _{CES}	–	–	100	μAdc	
		–	–	500		
		–	–	100		
Emitter Cutoff Current (V _{EB} = 9.0 Vdc, I _C = 0)	I _{EBO}	–	–	100	μAdc	
ON CHARACTERISTICS						
Base–Emitter Saturation Voltage (I _C = 2.0 Adc, I _B = 0.2 Adc) (I _C = 4.5 Adc, I _B = 0.9 Adc)	V _{BE(sat)}	–	0.82 0.92	1.1 1.25	Vdc	
Collector–Emitter Saturation Voltage (I _C = 2.0 Adc, I _B = 0.2 Adc)	V _{CE(sat)}	–	0.25 0.3	0.5 0.5	Vdc	
		–	0.35	0.7		
		–	0.35	0.8		
DC Current Gain (I _C = 1.0 Adc, V _{CE} = 5.0 Vdc)	h _{FE}	14	–	34	–	
		–	30	–		
		8.0	12	–		
		7.0	11	–		
		10	18	–		
		10	20	–		
DYNAMIC CHARACTERISTICS						
Current Gain Bandwidth (I _C = 0.5 Adc, V _{CE} = 10 Vdc, f = 1.0 MHz)	f _T	–	14	–	MHz	
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz)	C _{ob}	–	100	175	pF	
Input Capacitance (V _{EB} = 8.0 V)	C _{ib}	–	1750	2500	pF	
Dynamic Saturation Voltage: Determined 1.0 μs and 3.0 μs respectively after rising I _{B1} reaches 90% of final I _{B1} (see Figure 18)	(I _C = 2.0 Adc I _{B1} = 200 mAdc V _{CC} = 300 V)	1.0 μs	–	3.0	–	V
		3.0 μs	–	5.5	–	
	(I _C = 5.0 Adc I _{B1} = 0.9 Adc V _{CC} = 300 V)	1.0 μs	–	0.8	–	
		3.0 μs	–	1.4	–	
			V _{CE(dsat)}	–	3.3	–
				–	8.5	–
				–	0.4	–
				–	1.0	–

BUL147

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted) (continued)

Characteristic	Symbol	Min	Typ	Max	Unit	
SWITCHING CHARACTERISTICS: Resistive Load (D.C. $\leq 10\%$, Pulse Width = 20 μs)						
Turn-On Time	($I_C = 2.0 \text{ Adc}$, $I_{B1} = 0.2 \text{ Adc}$ $I_{B2} = 1.0 \text{ Adc}$, $V_{CC} = 300 \text{ V}$) ($T_C = 125^\circ\text{C}$)	t_{on}	–	200	350	ns
Turn-Off Time		t_{off}	–	1.0	2.5	μs
Turn-On Time	($I_C = 4.5 \text{ Adc}$, $I_{B1} = 0.9 \text{ Adc}$ $I_{B2} = 2.25 \text{ Adc}$, $V_{CC} = 300 \text{ V}$) ($T_C = 125^\circ\text{C}$)	t_{on}	–	85	150	ns
Turn-Off Time		t_{off}	–	1.5	2.5	μs
SWITCHING CHARACTERISTICS: Inductive Load ($V_{clamp} = 300 \text{ V}$, $V_{CC} = 15 \text{ V}$, $L = 200 \mu\text{H}$)						
Fall Time	($I_C = 2.0 \text{ Adc}$, $I_{B1} = 0.2 \text{ Adc}$ $I_{B2} = 1.0 \text{ Adc}$) ($T_C = 125^\circ\text{C}$)	t_{fi}	–	100	180	ns
Storage Time		t_{si}	–	1.3	2.5	μs
Crossover Time		t_c	–	210	350	ns
Fall Time	($I_C = 4.5 \text{ Adc}$, $I_{B1} = 0.9 \text{ Adc}$ $I_{B2} = 2.25 \text{ Adc}$) ($T_C = 125^\circ\text{C}$)	t_{fi}	–	80	150	ns
Storage Time		t_{si}	–	1.6	3.2	μs
Crossover Time		t_c	–	170	300	ns
Fall Time	($I_C = 4.5 \text{ Adc}$, $I_{B1} = 0.9 \text{ Adc}$ $I_{B2} = 0.9 \text{ Adc}$) ($T_C = 125^\circ\text{C}$)	t_{fi}	60	–	180	ns
Storage Time		t_{si}	2.6	–	3.8	μs
Crossover Time		t_c	–	200	350	ns

TYPICAL STATIC CHARACTERISTICS

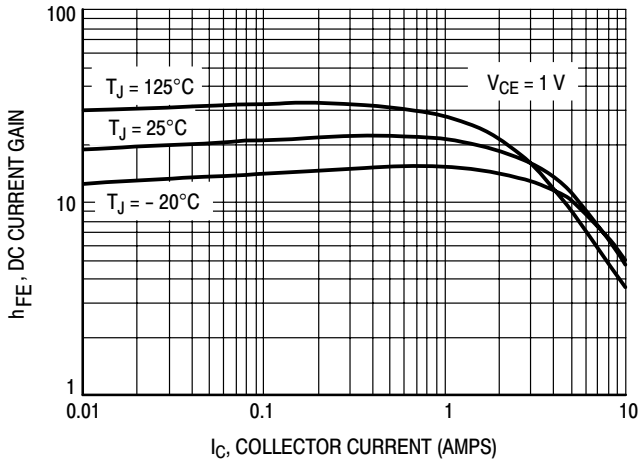


Figure 1. DC Current Gain @ 1 Volt

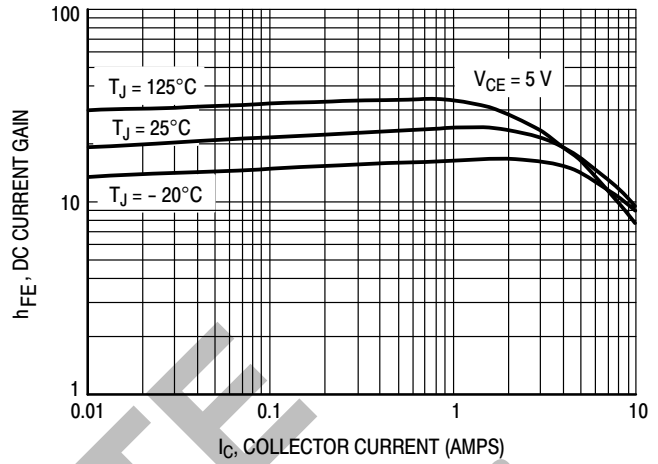


Figure 2. DC Current Gain @ 5 Volts

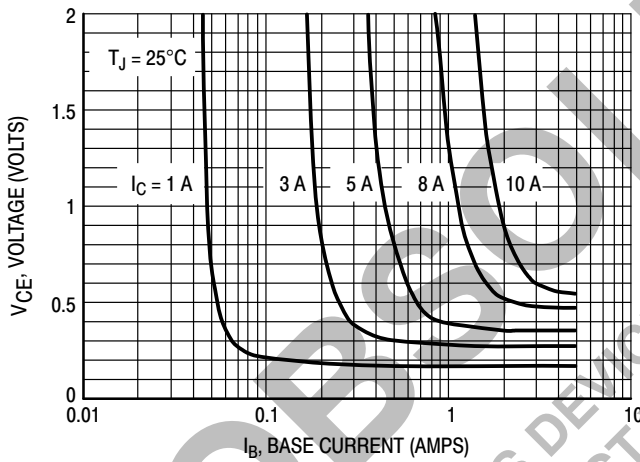


Figure 3. Collector Saturation Region

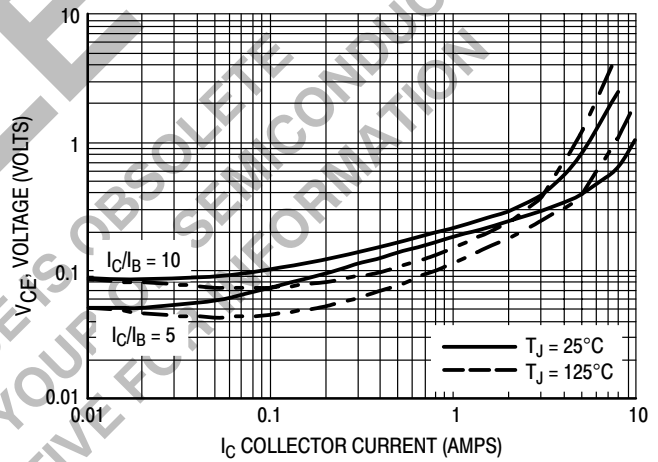


Figure 4. Collector-Emitter Saturation Voltage

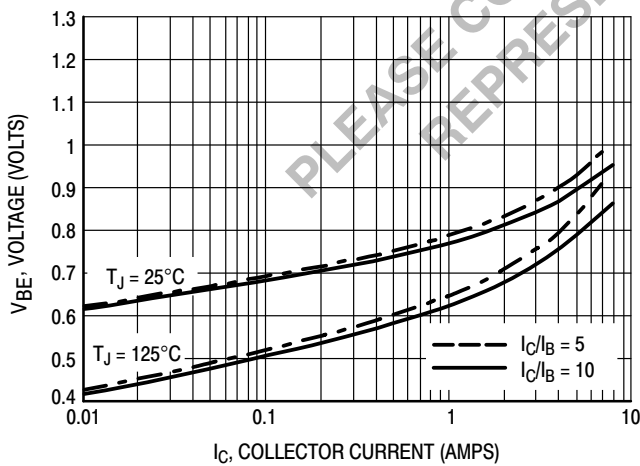


Figure 5. Base-Emitter Saturation Region

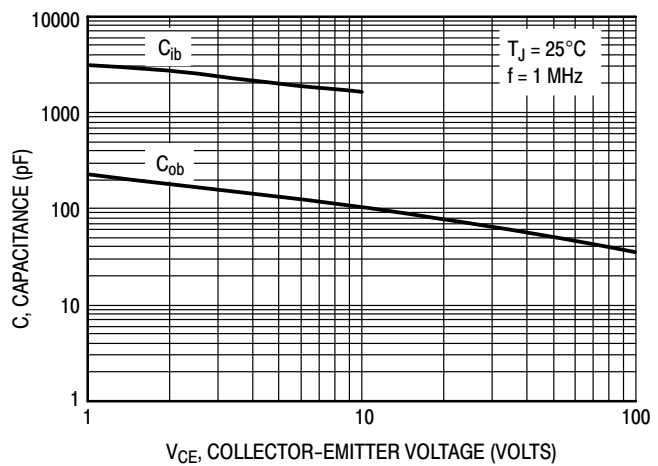


Figure 6. Capacitance

TYPICAL SWITCHING CHARACTERISTICS
($I_{B2} = I_C/2$ for all switching)

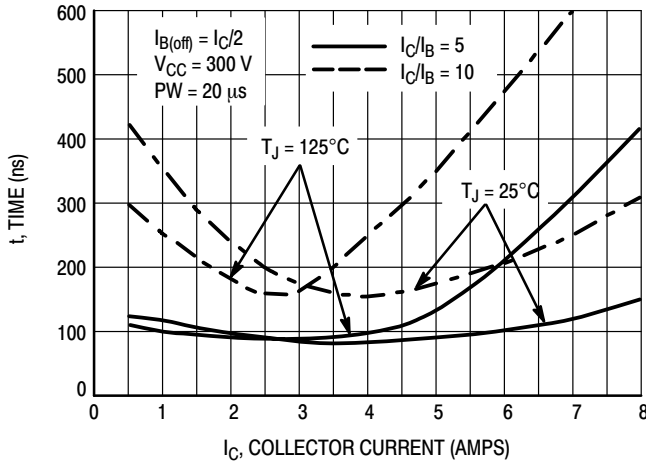


Figure 7. Resistive Switching, t_{on}

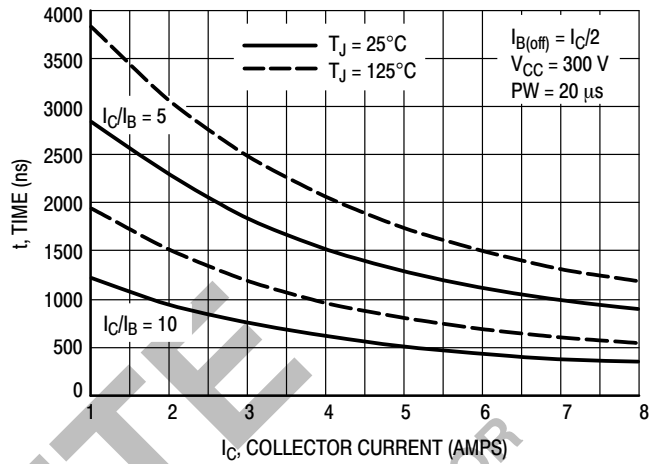


Figure 8. Resistive Switching, t_{off}

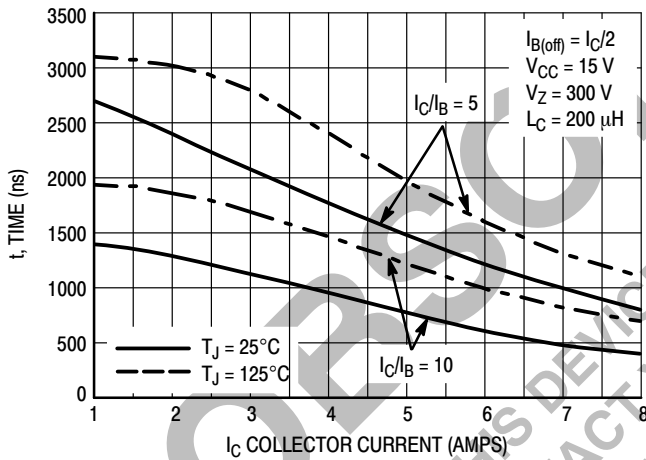


Figure 9. Inductive Storage Time, t_{si}

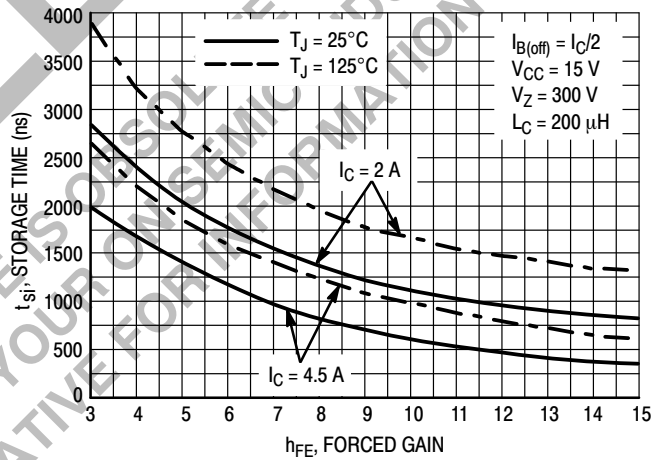


Figure 10. Inductive Storage Time, $t_{si}(h_{FE})$

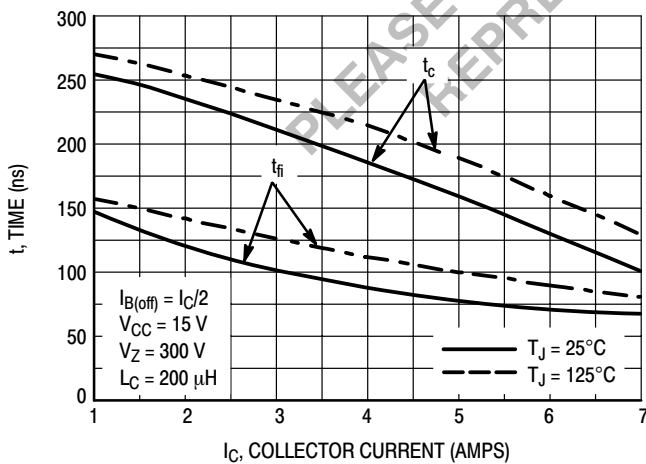


Figure 11. Inductive Switching, t_c and t_{fi}
 $I_C/I_B = 5$

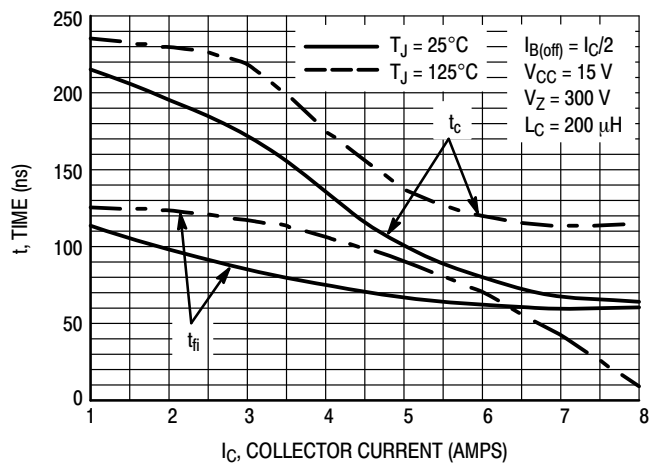


Figure 12. Inductive Switching, t_c and t_{fi}
 $I_C/I_B = 10$

TYPICAL SWITCHING CHARACTERISTICS
($I_{B2} = I_C/2$ for all switching)

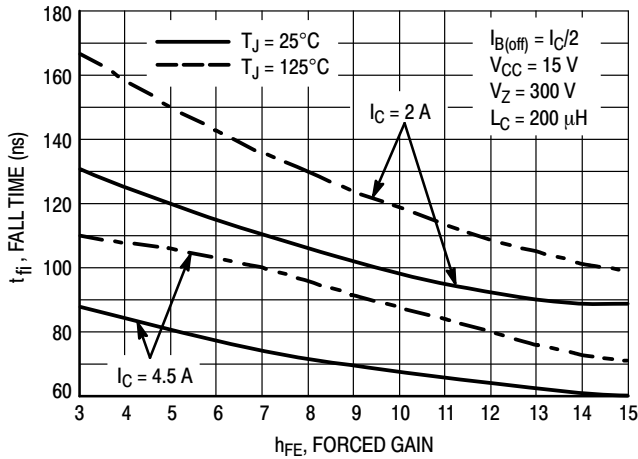


Figure 13. Inductive Fall Time

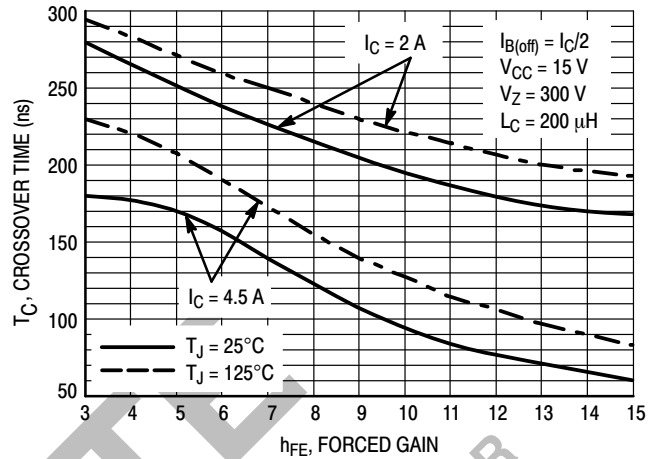


Figure 14. Inductive Crossover Time

GUARANTEED SAFE OPERATING AREA INFORMATION

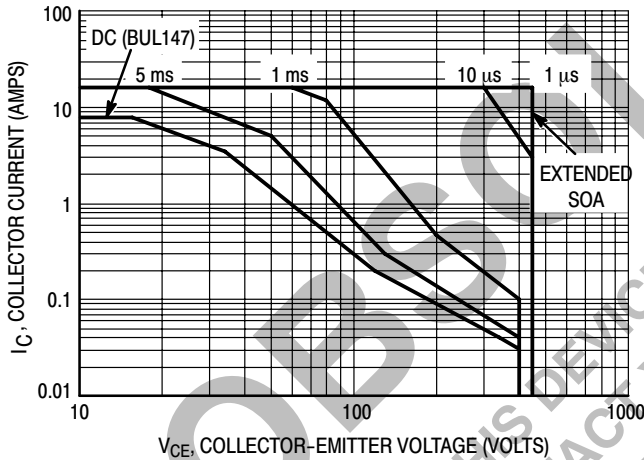


Figure 15. Forward Bias Safe Operating Area

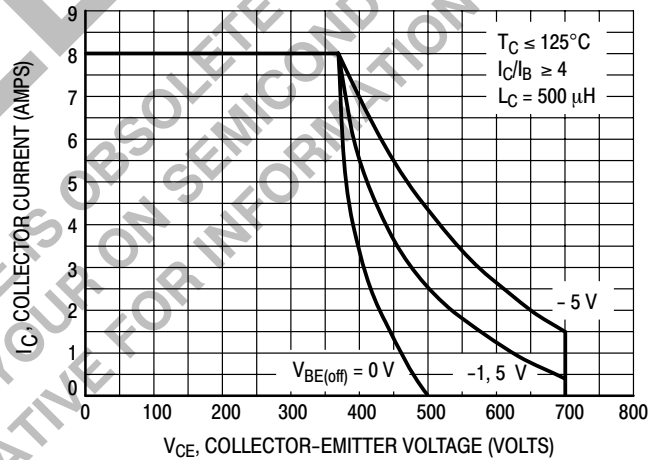


Figure 16. Reverse Bias Switching Safe Operating Area

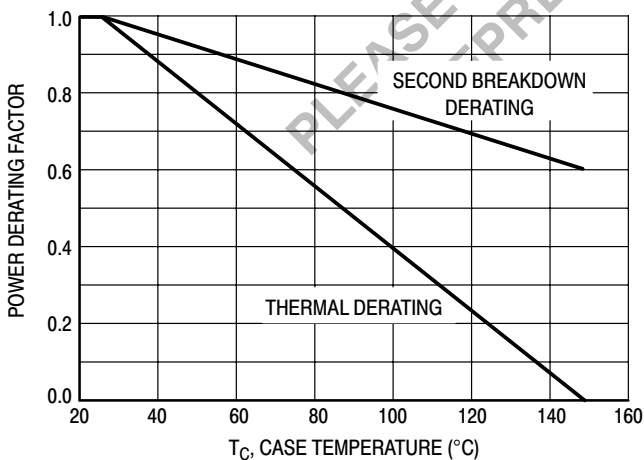


Figure 17. Forward Bias Power Derating

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate. The data of Figure 15 is based on $T_C = 25^\circ\text{C}$; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C > 25^\circ\text{C}$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown in Figure 15 may be found at any case temperature by using the appropriate curve on Figure 17. $T_{J(pk)}$ may be calculated from the data in Figure 20. At any case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown. For inductive loads, high voltage and current must be sustained simultaneously during turn-off with the base-to-emitter junction reverse-biased. The safe level is specified as a reverse-biased safe operating area (Figure 16). This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode.

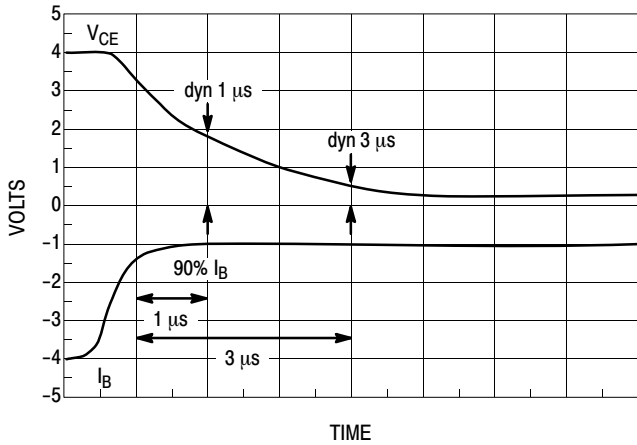


Figure 18. Dynamic Saturation Voltage Measurements

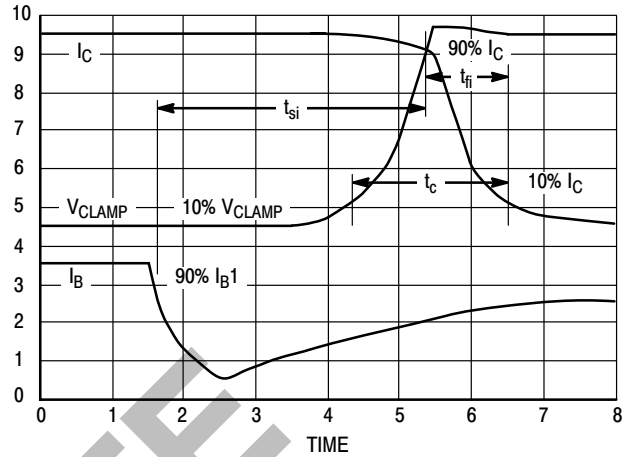
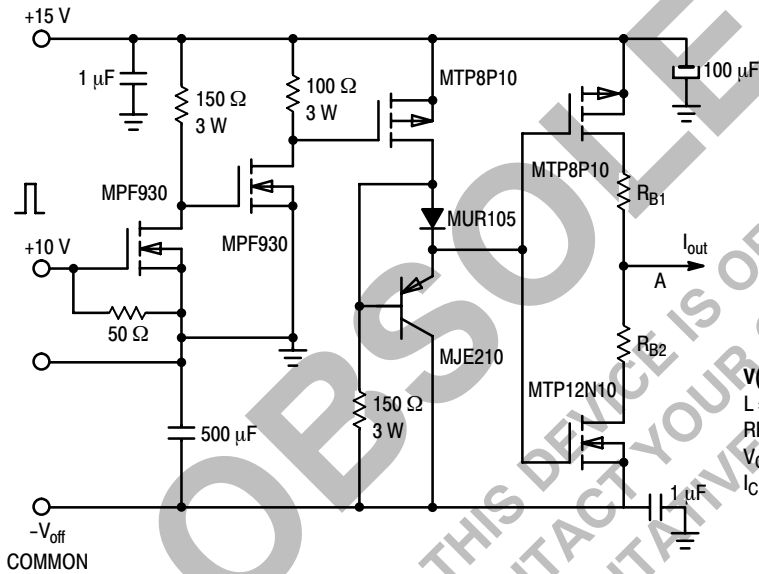


Figure 19. Inductive Switching Measurements



INDUCTIVE SWITCHING	RBSOA
$L = 10 \text{ mH}$	$L = 500 \mu\text{H}$
$RB2 = \infty$	$RB2 = 0$
$V_{CC} = 20 \text{ VOLTS}$	$V_{CC} = 15 \text{ VOLTS}$
$I_C(\text{pk}) = 100 \text{ mA}$	$RB1 \text{ SELECTED FOR DESIRED } I_{B1}$
	$RB1 \text{ SELECTED FOR DESIRED } I_{B1}$

Table 1. Inductive Load Switching Drive Circuit

TYPICAL THERMAL RESPONSE

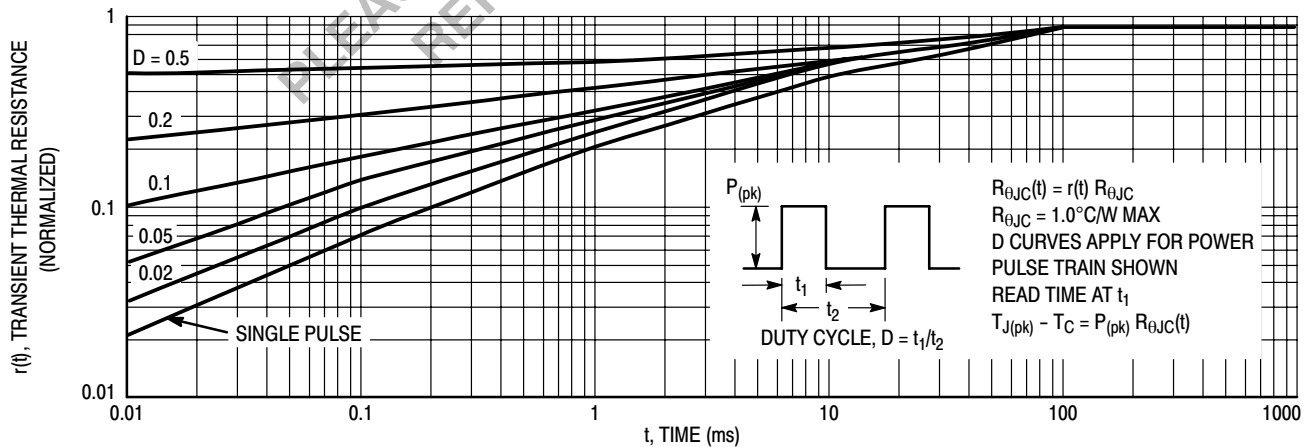
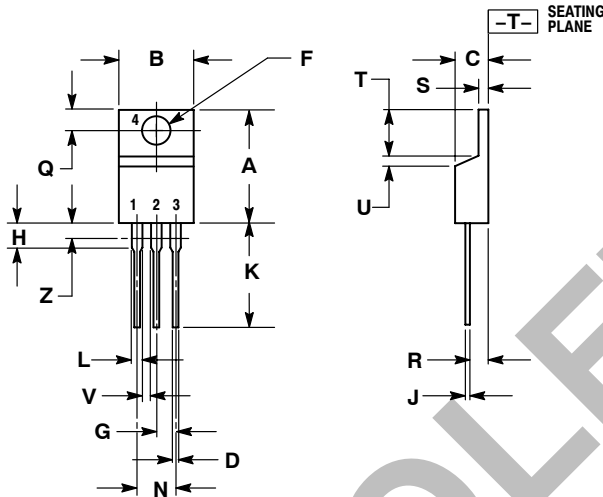


Figure 20. Typical Thermal Response ($Z_{\theta JC}(t)$) for BUL147

BUL147

PACKAGE DIMENSIONS

TO-220AB
CASE 221A-09
ISSUE AA



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

STYLE 1:

- PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

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